

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Marvin A. DENMAN</td> <td>09/19/2013</td> </tr> <tr> <td>Dennis K. MA</td> <td>09/19/2013</td> </tr> <tr> <td>Stephen David GLASER</td> <td>09/19/2013</td> </tr> </tbody> </table>		Name	Execution Date	Marvin A. DENMAN	09/19/2013	Dennis K. MA	09/19/2013	Stephen David GLASER	09/19/2013
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Stephen David GLASER	09/19/2013								
RECEIVING PARTY DATA									
Name:	NVIDIA CORPORATION								
Street Address:	2701 San Tomas Expressway								
City:	Santa Clara								
State/Country:	CALIFORNIA								
Postal Code:	95050								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14031776</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14031776				
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Application Number:	14031776								
CORRESPONDENCE DATA									
Fax Number:	7136234846								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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Email:	kneil@pattersonsheridan.com, PSDocketing@pattersonsheridan.com								
Correspondent Name:	Patterson & Sheridan, LLP.								
Address Line 1:	3040 Post Oak Blvd.								
Address Line 2:	Suite 1500								
Address Line 4:	Houston, TEXAS 77056								
ATTORNEY DOCKET NUMBER:	NVDA/AU-13-0349-US2								
NAME OF SUBMITTER:	John C. Carey								
Signature:	/John C. Carey/								

OP \$40.00 14031776

Date:

09/20/2013

Total Attachments: 4

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ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Marvin A. DENMAN, residing at
1 Meadow Way
Round Rock, Texas 78664

Dennis K. MA, residing at
10404 Canyon Vista Way,
Austin, Texas 78726

Stephen David GLASER, residing at
1757 15th Avenue
San Francisco, California 94122

(hereinafter referred to as Assignor), has invented a certain invention entitled:

TECHNIQUE FOR SCALING THE BANDWIDTH OF A PROCESSING ELEMENT TO MATCH THE BANDWIDTH OF AN INTERCONNECT

enclosed herewith or for which application for Letters Patent in the United States under Application No. _____, filed on _____, and

WHEREAS, **NVIDIA CORPORATION**, a Corporation of the State of Delaware having a place of business at 2701 San Tomas Expressway, Santa Clara, California 95050 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignor, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, conventional, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefore and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its

successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

5. I hereby authorize and request my attorneys, Patterson & Sheridan LLP, of 3040 Post Oak Blvd, Suite 1500, Houston Texas 77056, to insert above in parentheses (Application No. and Filing Date) the filing date and application number of said application when known.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) Sept. 19, 2013 
Marvin A. DENMAN

2) Sept 19, 2013 
Dennis K. MA

3) _____, 2013 _____
Stephen David GLASER

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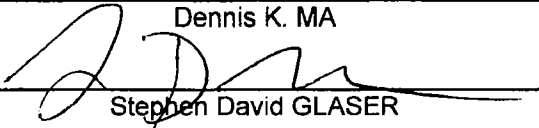
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1)	_____ , 2013	_____
		Marvin A. DENMAN
2)	_____ , 2013	_____
		Dennis K. MA
3)	19 September , 2013	
		Stephen David GLASER